Texas Instruments

Reliability Estimator

	Early life failure rate	MTBF / FIT		Early life failure rate sup	
Part number	ELFR-DPPM	MTBF	FIT	Conf level	Test temp
TPS51206DSQ	19	1x 10^{10}	0.1	60	125

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TI is providing this data for your convenience. However, we want to make clear the significant limitations of its usefulness as an indicator of how devices may perform in various applications.

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pporting data		MTBF / FIT supporting data					
Sample size	Fails	Usage temp	Conf level	Activation energy	Test temp	Test duration (hours)	Sample size
48872	0	55	60	0.7	125	1000	139267

Fails	
0	